

Table CE1 – Maximum Ratings

Part Number	IEC61000-4-2, level 4 (ESD Withstand)		Temperature	
	Contact (kV)	Air (kV)	Operating (°C)	Storage (°C)
SESD0201P1BN-0400-090	±10*	±16	-40 to +125	-40 to +125
SESD0402P1BN-0450-090	±10*	±16	-40 to +125	-40 to +125

Table CE2 – Electrical Characteristics @ T=25°C

Part Number	Input Capacitance*		Leakage Current (max) I _L @ V _{RWM} = 6.0V (µA)	Breakdown Voltage (min) V _{br} @ I _T [†] = 1mA (V)	Working Reverse Voltage V _{RWM} @ peak (V)	Clamping Voltage (typ) V _{CL} @ I _{pp} =2A, tp=(8/20µs) (V)*
	Typ (pF)	Max (pF)				
SESD0201P1BN-0400-090	4.0	5.0	1.0	9.0	6.0	+10.0
SESD0402P1BN-0450-090	4.5	5.5	1.0	9.0	6.0	+10.0

* @ Vr=0V, f=1MHz

† V_{br} is measured at test current I_T

Figure CE1 – ESD Clamping Voltage - 8kV Contact

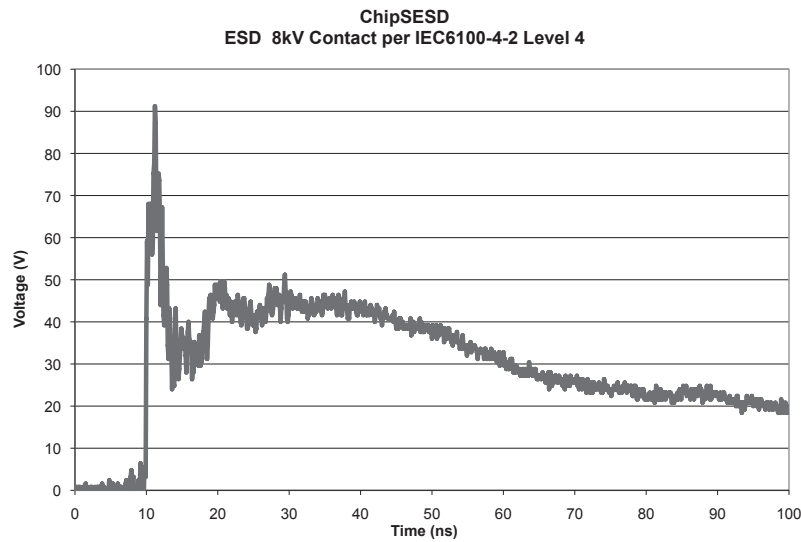
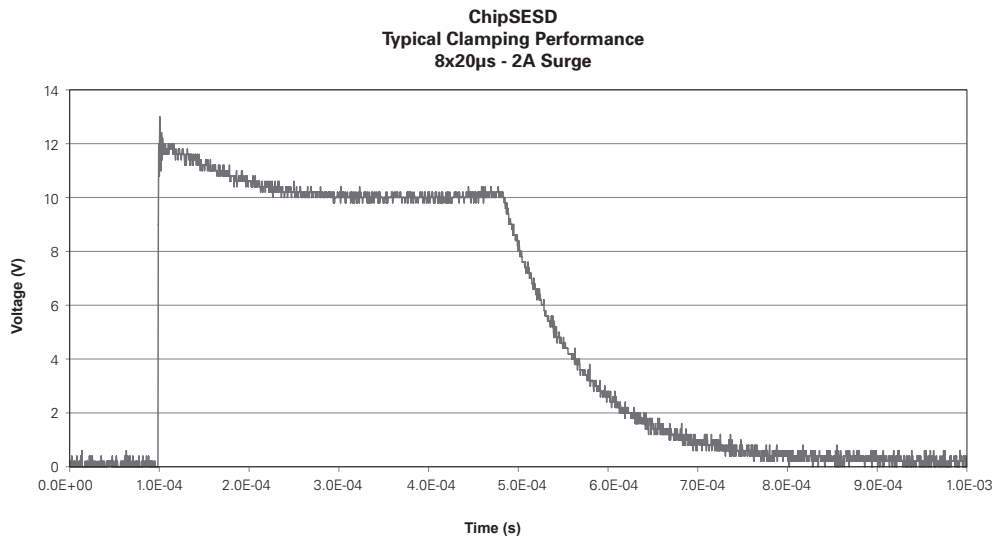


Figure CE2 – ESD Clamping Voltage - 8x20µs, 2A Surge



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Table CE3 - Dimensions in Millimeters and (Mils)*

Part Number	A	B	C	D	Figure
SESD0201P	0.60 ± 0.05	0.30 ± 0.05	0.30 ± 0.05	0.21 ± 0.07	CE3
	(23.62 ± 2.00)	(11.81 ± 2.00)	(11.81 ± 2.00)	(8.27 ± 2.80)	
SESD0402P	1.10 ± 0.10	0.50 ± 0.10	0.50 ± 0.10	0.25 ± 0.15	CE3
	(43.31 ± 0.40)	(19.69 ± 4.00)	(19.69 ± 4.00)	(9.84 ± 6.00)	

* Round off approximation

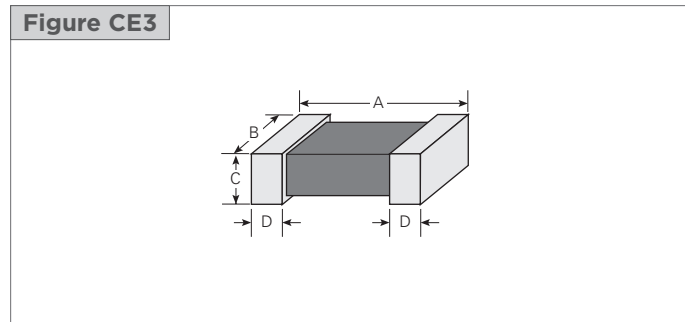


Table CE4 - PCB Pad Layout in Millimeters and (Mils)*

Part Number	L	S	W	Figure
SESD0201P	0.28 ± 0.01	0.19 ± 0.01	0.30 ± 0.01	CE4
	(11.00 ± 0.40)	(7.50 ± 0.40)	(11.80 ± 0.40)	
SESD0402P	0.61 ± 0.05	0.52 ± 0.05	0.50 ± 0.05	CE4
	(24.00 ± 2.00)	(21.00 ± 2.00)	(20.00 ± 2.00)	

* Round off approximation

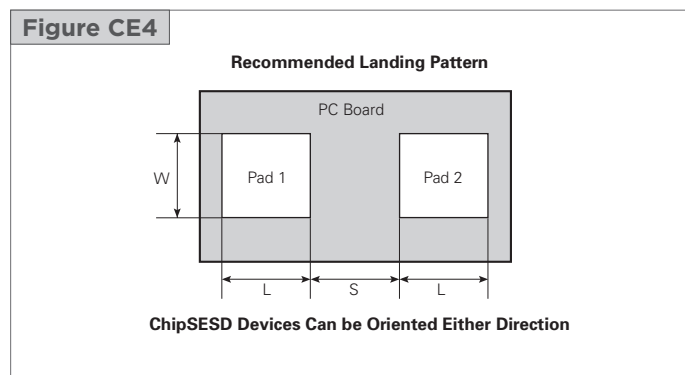


Table CE5 – Tape Specifications

Tape Dimension EIA Mark	SESD0201P1BN-0400-090	SESD0402P1BN-0450-090
	Dimension (mm)	Dimension (mm)
A	0.35 ± 0.02	0.58 ± 0.03
B	0.67 ± 0.02	1.20 ± 0.03
D	1.55 ± 0.05	1.55 ± 0.05
E	1.75 ± 0.05	1.75 ± 0.05
F	3.50 ± 0.05	3.50 ± 0.05
W	8.00 ± 0.10	8.00 ± 0.10
P ₀	4.00 ± 0.10	4.00 ± 0.10
P ₁	2.00 ± 0.05	2.00 ± 0.05
P ₂	2.00 ± 0.05	2.00 ± 0.05
T	0.42 ± 0.03	0.60 ± 0.03

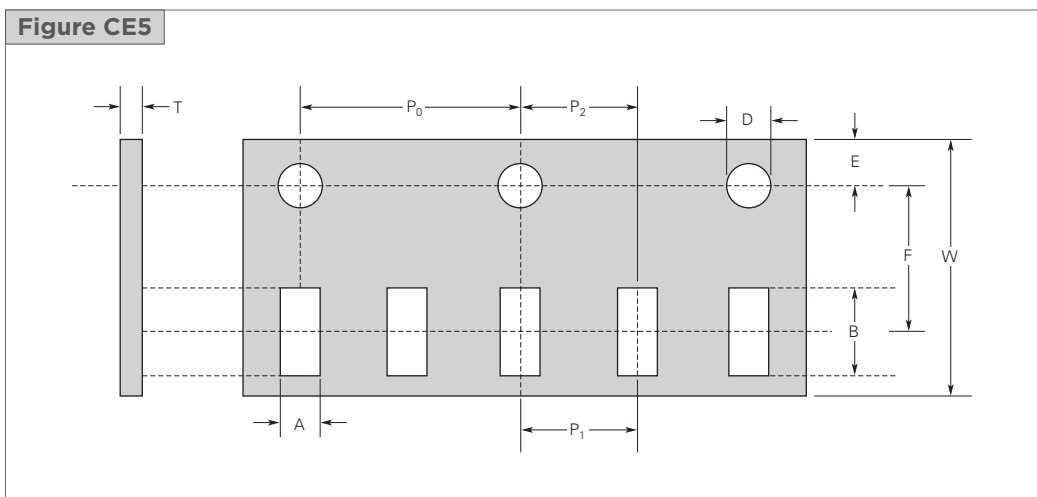
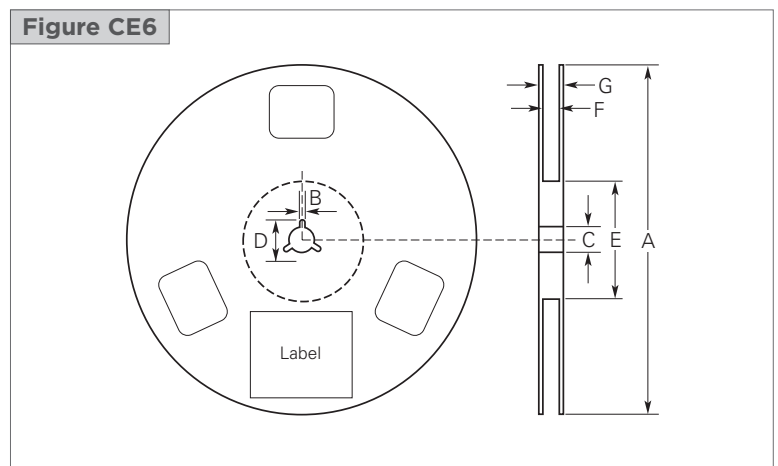


Table CE6 – Reel Specifications

Reel Dimension EIA Mark	Dimension (mm)
A	178.0 ± 2.0
B	2.0 ± 0.5
C	13.0 ± 0.5
D	21.0 ± 0.8
E	62.0 ± 1.5
F	9.0 ± 0.5
G	13.0 ± 1.0

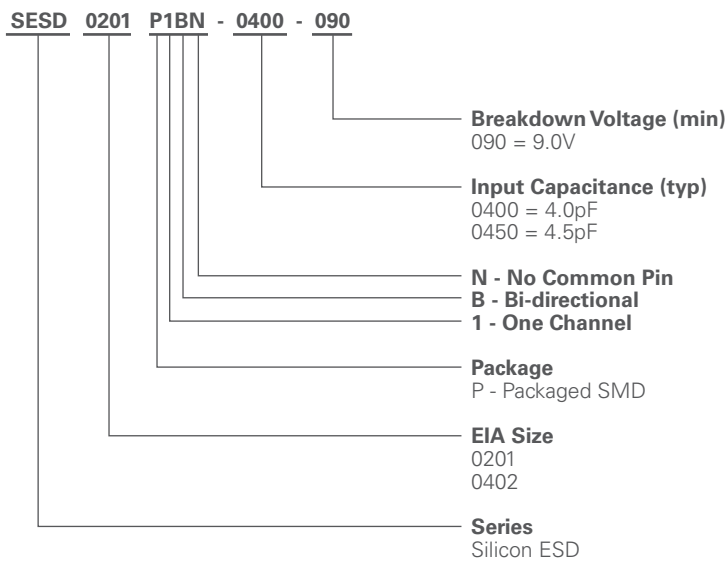


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Definition of Terms

I_L	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Working Peak Reverse Voltage
V_{br}	Breakdown Voltage @ I_T
I_T	Test Current
V_{CL}	Clamping Voltage

Part Numbering System



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